

Notice of References Cited	Application/Control No. 10/560,073	Applicant(s)/Patent Under Reexamination MASUKO ET AL.	
	Examiner ANISH DESAI	Art Unit 1787	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	Shinjiro Fujii, "Die Bonding Adhesive and Method for Fabricating Semiconductor Devices", English translation of JP 2000-104040, 04/11/2000.
	V	Aichi, Katsuhide et al., "Adhesive Sheet for Sticking Wafer and Semiconductor Device", Machine translation of JP 2002-158276, 05/31/2002.
	W	Masuko Takashi et al., "Adhesive Film, Its Manufacturing Method and Semiconductor Device Having Adhesive Film", Machine translation of JP 2002-121530A, 04/26/2002.
	X	Sato Kazuya et al., "Adhesive Film, Method for Producing the Same and Method for Bonding", Machine translation of JP 2001-303015A, 10/31/2001.

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.